molex

Sentrality High-Power Pin and Socket Connector

Molex's Sentrality Interconnect System introduces the eye-of-needle (EON) press-fit socket, a mezzanine-style, board-to-board and board-to-busbar connector that offers self-aligning without soldering, for enhanced design flexibility

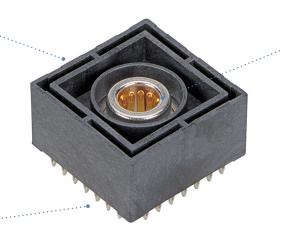


Sentrality EON Press-Fit Socket

FEATURES AND ADVANTAGES

Designed with a uniform flat top surface

Provides for flat-rock processing during insertion into the printed circuit board and saves money and time as customers do not have to purchase custom tooling to press the connector into the printed circuit board



Self-aligning capability

Allows Sentrality socket to float between wave springs that allow the socket to freely move radially +/- 1.00mm parallel to the plane of the PCBA during mating, helping to ensure no contact beam deformation

Eye-of-needle press fit tails

Enable high-quality, solderless electrical connections







Sentrality EON Press-Fit Sockets

in 3.40, 6.00, 8.00 and 11.00mm



MARKETS AND APPLICATIONS

Telecommunications/Networking

Servers Storage

Data Centers

Servers
Data Storage
Power distribution units (PDUs)
Uninterruptable power supplies
Switches
Routers
Environmental control equipment

Industrial Automation

Battery-charging stations DC-to-AC inverters Robotics



Data Center Servers



Industrial Inverters



Uninterruptable Power Supply



Sentrality High-Power Pin and Socket Connector

SPECIFICATIONS

REFERENCE INFORMATION

Packaging: Tape and reel, tray or bag depending on part number; see packaging specifications for details

UL File No.: E29179 CSA File No.: 70184994

Use With: Printed circuit boards and busbars

Designed In: Millimeters

RoHS: Yes Halogen Free: Yes

ELECTRICAL (3.40MM SIZE)

Voltage (max.): 600V Current (max.): 75.0A

Contact Resistance (max.): 0.25 milliohms

MECHANICAL (3.40MM SIZE)

Mating Force (max.): 20.0N Unmating Force (min.): 6.0N

OmniGlide Alignment Force (max.): 10.0N Durability (min.): 200 mating cycles

ELECTRICAL (8.00MM SIZE)

Voltage (max.): 600V Current (max.): 200.0A

Contact Resistance (max.): 0.20 milliohms

MECHANICAL (8.00MM SIZE)

Mating Force (max.): 40.0N Unmating Force (min.): 10.0N

OmniGlide Alignment Force (max.): 15.0N Durability (min.): 200 mating cycles

PHYSICAL

Eye-of-Needle Socket Housing: LCP (black)
Contact: High-performance Copper (Cu) Alloy
Plating:

Socket Contact Area—Gold (Au)

Eye-of-Needle Socket Compliant Tail—Silver (Ag)

Pin - Silver (Ag)

PCB Thickness (min.): 1.58mm

Busbar Thickness (min.): 1.50mm

Operating Temperatures: -40 to +125°C

ELECTRICAL (6.00MM SIZE)

Voltage (max.): 600V Current (max.): 120.0A

Contact Resistance (max.): 0.20 milliohms

MECHANICAL (6.00MM SIZE)

Mating Force (max.): 30.0N Unmating Force (min.): 7.0N

OmniGlide Alignment Force (max.): 10.0N Durability (min.): 200 mating cycles

ELECTRICAL (11.00MM SIZE)

Voltage (max.): 600V Current (max.): 350.0A

Contact Resistance (max.): 0.40 milliohms

MECHANICAL (11.00MM SIZE)

Mating Force (max.): 55.0N Unmating Force (min.): 10.0N

OmniGlide Alignment Force (max.): 70.0N Durability (min.): 200 mating cycles